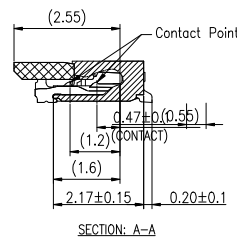
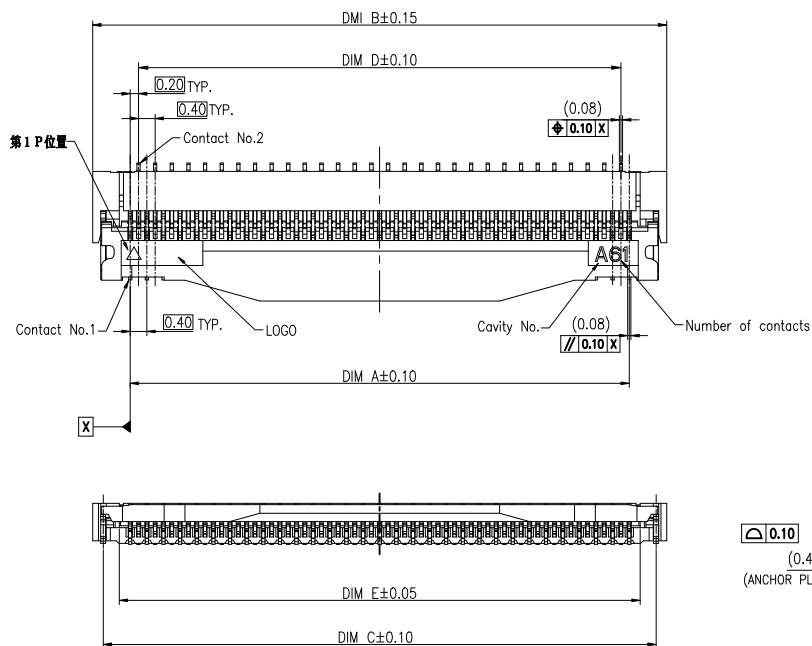
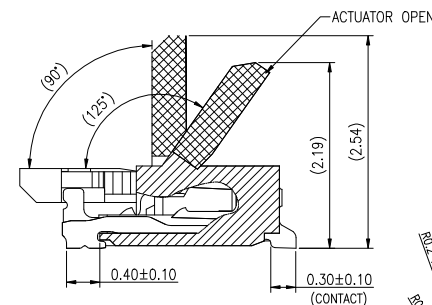
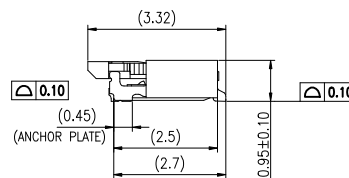


REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		

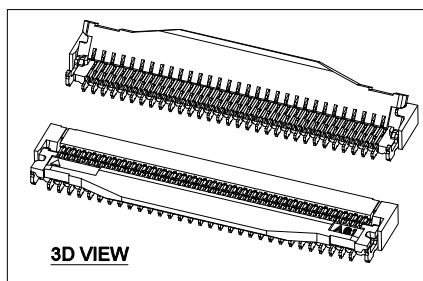


FPC CONFIGURATION (REFERENCE EXAMPLE) (FREE)

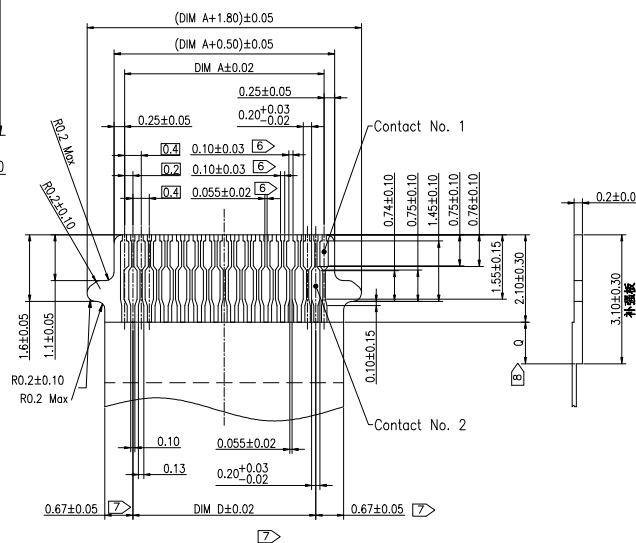
MATERIAL NAME	MATERIAL	THICKNESS(um)
COVERING FILM LAYER	POLYIMIDE 1 mil	61
COVER ADHESIVE		61
SURFACE TREATMENT	1um To 6um NICKEL UNDERPATED 0.2um GOLD PLATED	(4)
COPPER FOIL	Cu 1/3 oz	12
BASE ADHESIVE	HEAT-HARDENED ADHESIVE	No adhesion mate
BASE FILM	POLYIMIDE 1 mil	61
REINFORCEMENT MATERIAL ADHESIVE	HEAT-HARDENED ADHESIVE	30
STIFFENER	POLYIMIDE 5 mil	125



No.	Dimensions				
	A	B	C	D	E
31	6.00	7.80	7.29	5.60	6.53
35	6.80	8.60	8.09	6.40	7.33
45	8.80	10.60	10.09	8.40	9.33
51	10.00	11.80	11.29	9.60	10.53
61	12.00	13.80	13.29	11.60	12.53
71	14.00	15.80	15.29	13.60	14.53

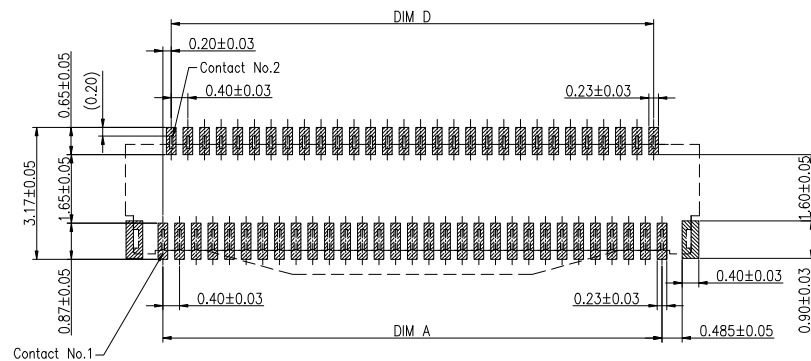


1. MATERIAL:
HOUSING: LCP UL 94V-0 COLOR IS BEIGE
ACTUATOR: PA UL94HB COLOR IS OR BLACK
CONTACTS: COPPER ALLOY
PEG: COPPER ALLOY
2. PLATING:
2.1 CONTACT AREA:
GOLD FLASH ON CONTACT AREA
50~100U"NICKEL UNDER PLATING OVER ALL.
- 2.2 SOLDER AREA:
GOLD FLASH ON CONTACT AREA
50~100U"NICKEL UNDER PLATING OVER ALL.
- 2.3 FITTING:
100~200u"MATT TIN PLATING ON SOLDER
TAILS(LEAD FREE)
50~100U"NICKEL UNDER PLATING OVER ALL.
- 3.PART NO
OPERATING VOLTAGE: 30Vrms AC
CURRENT RATING: 0.2A DC
OPERATING TEMPERATUER: -55°C~+85°C
4. The "★"number with asterisk is the
existing P of the mold



RECOMMENDED FPC 1:1

NOTE: ⑥ Shows recommended dimension when lead for plating is required.
⑦ Indicated tolerance is applicable to the exposed conductor.
⑧ Dimension Q must be 0.5mm minimum.



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05 / THICKNESS T=0.10mm

DESIGN:	Xiping Huang				广东国连电子有限公司 GUANGDONG GUOLIAN ELECTRONICS CO., LTD		
CHECK:	Ke Tian						
APPROVED:	Youquan Xu			TITLE:			
DIM	TOL	DIM	TOL	0.2翻盖 H0.9			
X.	±0.25	X°	±3.0°	PART NO. C0209-61-21LR1			
X.X	±0.20	X.X°					
X.XX	±0.15	X.XX°		REV. A SCALE: N/A UNIT: mm SHEET: 1/1 			
X.XXX		X.XXX°					